

Epoxy adhesive formulations

Epoxy adhesive is also called two part epoxy resin adhesive, which is composed of A-component epoxy resin and B-component curing agent

A component

Ingredients	Mass percentage	Ingredient description
Bisphenol A epoxy resin	50.0-55.0%	E44
Aluminum hydroxide (800 mesh)	20.0-25.0%	Filler
Silicon powder (1000 mesh)	15.0-20.0%	Filler
Iron oxide	1.0-3.0%	Filler

B component

Ingredients	Mass percentage	Ingredient description
Methyltetrahydrophthalic anhydride	18.0-25.0%	Curing agent
N,N-Dimethylbenzylamine	1.5-2.5%	Accelerator
Polyester polyurethane	5.0-7.0%	Toughener
BHT	1.0-1.5%	Antioxidant
Silicon powder (1000 mesh)	15.0-20.0%	Filler
Iron oxide	40.0-50.0%	Filler

If you need special formula epoxy adhesive, [please contact us](#), we will customize according to your needs